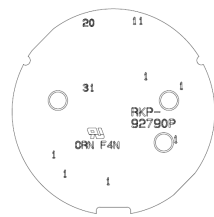
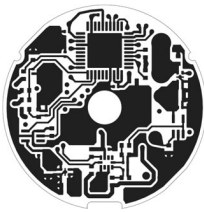
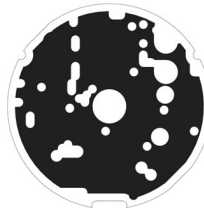
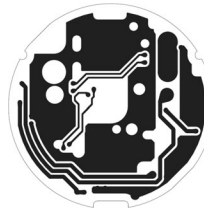
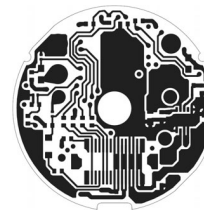


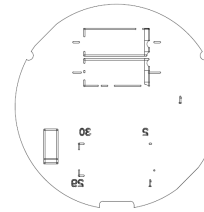
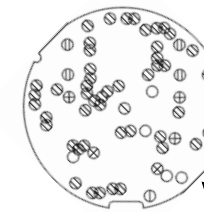
RKP-92790P

SILK PRINT FOR
PARTS SIDE

PARTS SIDE

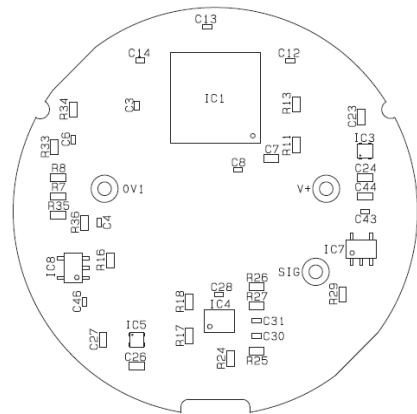
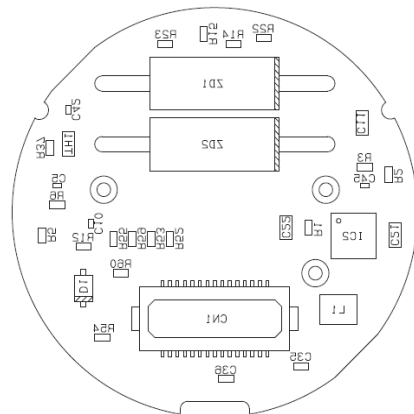
INNER LAYER
(2 LAYER)INNER LAYER
(3 LAYER)

SOLDERING SIDE

SILK PRINT FOR
SOLDEING SIDE

THROUGH HOLE

MARK	DIAGRAM	HOLE	MEMO
①	φ 0.3	TH	
○	φ 0.5	TH	
⊗	φ 0.7	TH	
⊗	φ 0.9	TH	
⊗	φ 1.3	TH	
⊕	φ 0.65	NTH	
①	φ 3.5	NTH	

All drawings are view of parts side
SCALE 1:1PARTS NAME FOR
PARTS SIDEPARTS NAME FOR
SOLDERING SIDE

SPECIFICATION FOR PCB

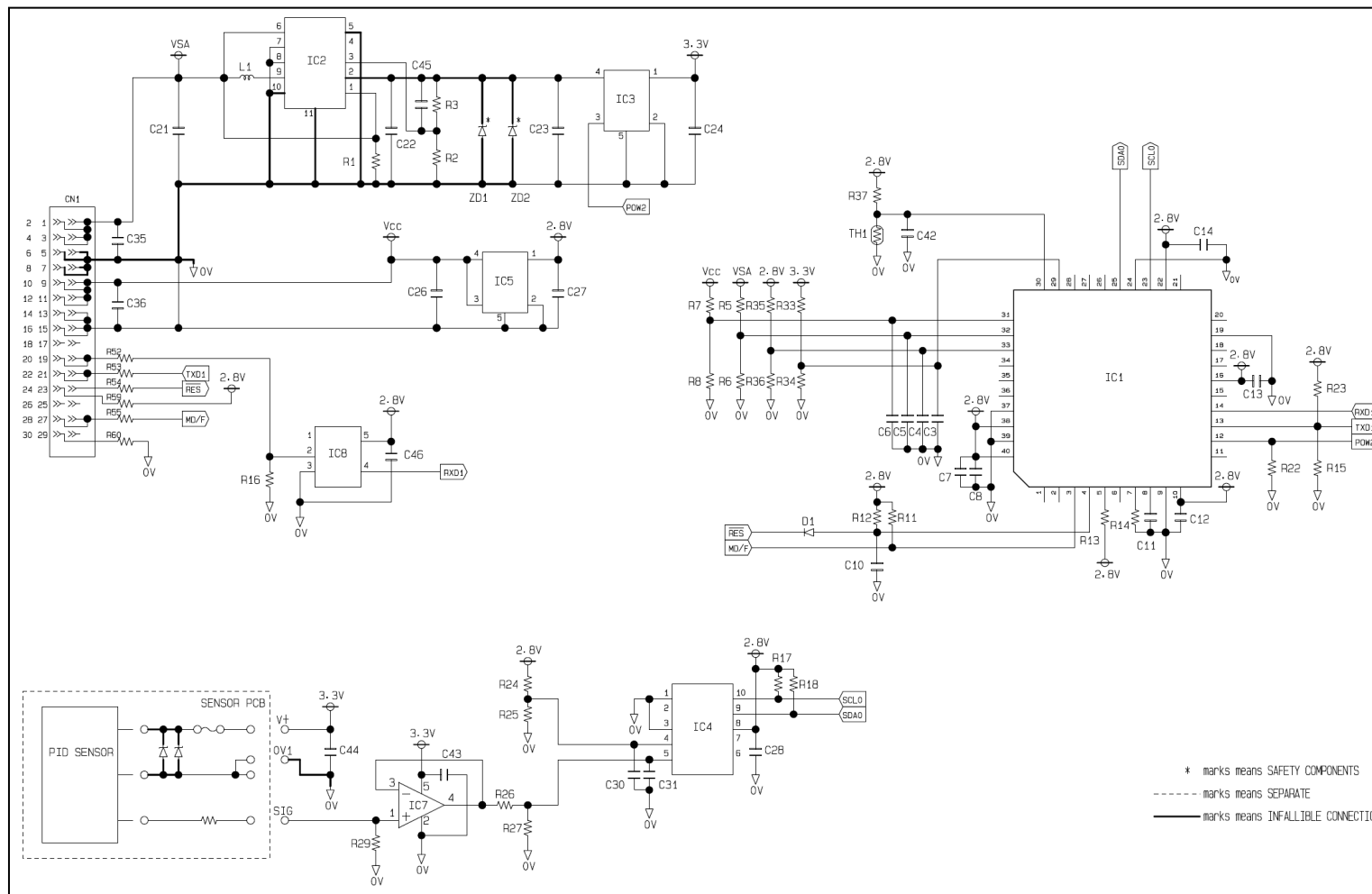
- PCB No. : RKP-92790P
- Material : Glass epoxy
- Thickness : 1.2mm
- Layer number : 4
- Thickness copper film : 35um
Surface : 35um, Inner : 35um
- Minimum conductor width : 0.2mm
- CTI : 100 above

PARTS LIST

Mark of drawing	Kind of parts	Rating / Model of parts	Remarks
IC1	IC(CPU)	R5F51113AGNF [RENESAS]	
IC2	IC(StepupDC/DCConverter)	TPS61020DRC [TI]	
IC3	IC(LDO)	S-1335A33-A4T2 [ABLIC]	
IC4	IC(A/D converter)	ADS1114IRUGR [TI]	
IC5	IC(LDO)	S-1335A28-A4T2 [ABLIC]	
IC7	IC(OPAMP)	TLV333IDCK [TI]	
IC8,	IC(Buffer)	SN74LVC1G17DCK [TI]	
D1	Schottky Barrier Diode	1PS76SB40 [NXP]	
ZD1,ZD2	Zener Diode	1N5338BG, ON Semiconductor Vz = 4.85 - 5.36V, 5W, Tj=200°C	*
TH1	Chip thermistor	Rt25 = 1k ohm -470 k ohm / 5%, B=3000K-5000K (1608)	
R1-R3,R5-R8, R11-R18,R22, R24-R27,R29, R33-R37,R52-R55 R59,R60	Chip fixed resistor or Chip jumper	30ohm - 10Mohm / 1%, 0.1W or 50m ohm max,1A (1005)	
C3-C7,C8,C10-C14, C21-C24,C26-C28, C30,C31,C35,C36, C42-C46	Chip multilayer capacitor	Total capacitance 14.4uFmax	
L1	Inductor	8.9uHmax (3225)	

* marked parts are Safety Components.

All components may be replaced with equivalent components or may not be mounted.



SCHEMATIC

注 記 NOTES		改版担当者 REV. BY	改版日 REVISED	名称 NAME
ZD1,2 Tj TH1 Rt25,size		小野圭	2021.6.10	DIGITAL PCB FOR MODEL PIF
改版回数 REV.	総頁数 PAGES			
1	1			
承認 APPROVED	検討 CHECKED	製図 DRAWN	作成日 DATE	図番 DWG. NO.
北村正英	小野圭	木村司	2021.4.7	E3-6991-6198-00-01K

RIKEN KEIKI

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